L Number	Hits	Search Text	DB	Time stamp
1	4	4783428.pn. 4878108.pn. 6006981.pn. 6646329.pn.	USPAT; US-PGPUB	2004/05/19 10:22
2	2526	438/15.ccls. 438/17.ccls. 438/111.ccls. 438/113.ccls. 438/463.ccls. 438/464.ccls.	USPAT; US-PGPUB	2004/05/19 10:34
3	3	(438/15.ccls. 438/17.ccls. 438/111.ccls. 438/113.ccls. 438/463.ccls. 438/464.ccls.) and (leadframe (lead adj frame) with laser) and (tape with reel) and (((semiconductor adj device) ic (integrated adj circuit)) with test$6)	USPAT; US-PGPUB	2004/05/19 11:12
4	4	(leadframe (lead adj frame) with laser) same (tape with reel) same (((semiconductor adj device) ic (integrated adj circuit)) with test$6)	USPAT; US-PGPUB	2004/05/19 10:46
5	385	((leadframe (lead adj frame)) with laser)	USPAT; US-PGPUB	2004/05/19 11:00
6	2	((leadframe (lead adj frame)) with laser) and (tape with reel) and (((semiconductor adj device) ic (integrated adj circuit)) with test$6)	USPAT; US-PGPUB	2004/05/19 10:44
8	20	(438/15.ccls. 438/17.ccls. 438/111.ccls. 438/113.ccls. 438/463.ccls. 438/464.ccls.) and (((leadframe (lead adj frame)) with laser))	USPAT; US-PGPUB	2004/05/19 10:47
9	7	((leadframe (lead adj frame)) with strip) same (laser with (dic$6 cut$7))	USPAT; US-PGPUB	2004/05/19 11:11
10	83	((leadframe (lead adj frame)) with strip) and (laser with (dic$6 cut$7))	USPAT; US-PGPUB	2004/05/19 12:23
11	0	(((leadframe (lead adj frame)) with strip) and (laser with (dic$6 cut$7))) and (tape with reel) and (((semiconductor adj device) ic (integrated adj circuit)) with test$6)	USPAT; US-PGPUB	2004/05/19 12:13
13	13	(((leadframe (lead adj frame)) with strip) and (laser with (dic$6 cut$7))) and ((tape with reel) (((semiconductor adj device) ic (integrated adj circuit)) with test$6))	USPAT; US-PGPUB	2004/05/19 12:25
14	7	(((leadframe (lead adj frame)) with strip) and (laser with (dic$6 cut$7))) and (tape reel spool) and (((semiconductor adj device) ic (integrated adj circuit)) with test$6)	USPAT; US-PGPUB	2004/05/19 12:13
15	158	(leadframe (lead adj frame)) same (laser with (dic$6 cut$7))	USPAT; US-PGPUB	2004/05/19 12:47
16	13	((leadframe (lead adj frame)) same (laser with (dic$6 cut$7))) and ((tape with reel) (((semiconductor adj device) ic (integrated adj circuit)) with test$6))	USPAT; US-PGPUB	2004/05/19 12:25
19	0	(4783428.pn. 4878108.pn. 6006981.pn. 6646329.pn.) and underfill	USPAT; US-PGPUB	2004/05/19 12:43
20	1	20020171126.pn. and underfill	USPAT; US-PGPUB	2004/05/19 12:43
21	188	(leadframe (lead adj frame)) and (laser with (dic$6 cut$7))	EPO; JPO; DERWENT; IBM_TDB	2004/05/19 12:47
22	3	(leadframe (lead adj frame)) and (laser with (dic$6 cut$7)) and test$6	EPO; JPO; DERWENT; IBM_TDB	2004/05/19 12:56
23	12	(leadframe (lead adj frame)) and (laser with (dic$6 cut$7)) and (tape reel spool)	EPO; JPO; DERWENT; IBM_TDB	2004/05/19 12:56
48	2	(strip near2 test$6) same (isolat$6 near2 gate)	USPAT; US-PGPUB	2004/05/19 15:54
49	97	test$6 with (isolat$6 near2 gate)	USPAT; US-PGPUB	2004/05/19 16:29
50	89	(test$6 with (isolat$6 near2 gate)) and (semiconductor silicon wafer package integrated)	USPAT; US-PGPUB	2004/05/19 16:30
52	107	(test$6 with (pad near2 gate)) and (semiconductor silicon wafer package integrated)	USPAT; US-PGPUB	2004/05/19 16:30
53	1	(strip near2 test$6) with (pad near2 gate)	USPAT; US-PGPUB	2004/05/19 16:31
54	1	(strip near2 test$6) same (pad near2 gate)	USPAT; US-PGPUB	2004/05/19 16:31

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51	113	test$6 with (pad near2 gate)	USPAT; US-PGPUB	2004/05/19 16:32